



深圳市英尚智能技术有限公司
SHENZHEN INSUN INTELLIGENT TECHNOLOGY CO.,LTD

SPI
系列



高智能
HIGH INTELLIGENCE

高清晰
HIGH DEFINITION

高真彩
HIGH COLOR

MORE Accurate
Professional
Suitable
更精准、更专业、更适合

A Global Leading Brand Of
Professional Visual Manufacturer

利用光学原理以及三角测量法来检查印刷锡膏的状态，精确分析生产过程中的不良现象及原因，来帮助提高生产品质

Using optical principle and triangulation method to check the state of solder paste printing and accurately analyze the defects phenomena and causes in the production process, and improve the quality of production

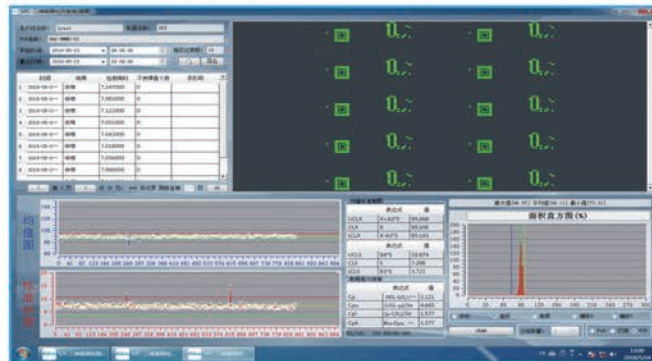
产品优点

PRODUCT ADVANTAGES



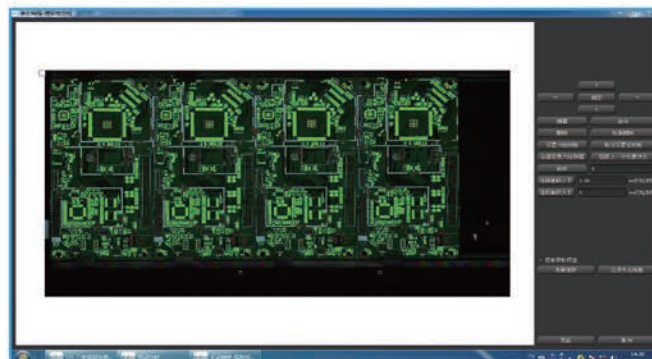
强大的SPC管理系统，一目了然

Strong SPC management system, easy to read



快速、直观的编程方式

Fast and intuitive programming



产品优点

PRODUCT ADVANTAGES



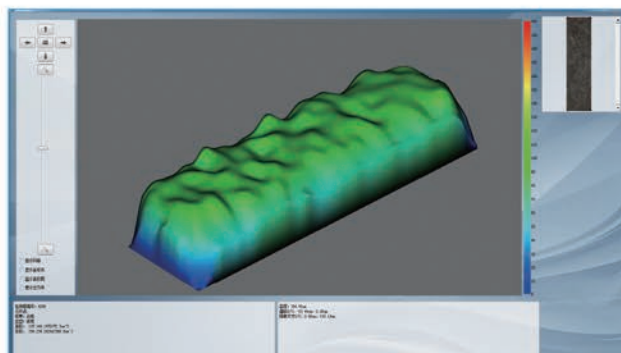
双向投影系统，有效消除阴影

Two way projection system, effectively eliminate the shadow



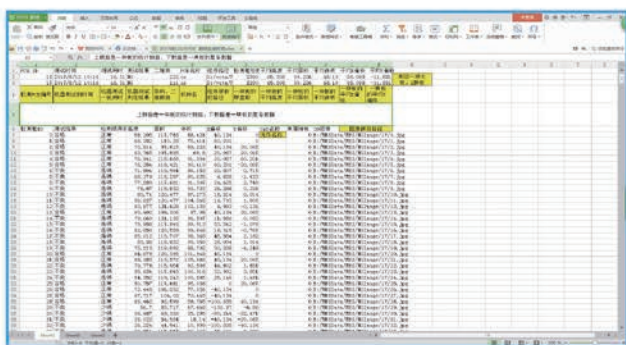
真彩色三维立体图像

True color 3D image



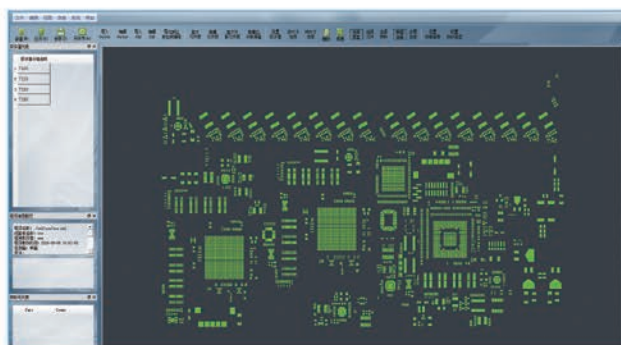
MES数据生成，在线实时监控生产

MES data generation, online real-time monitoring of production



离线编程功能，实时在线测试时，同步编程

Offline programming function, real-time online testing , while programming



应用领域

FIELD OF APPLICATION



主板、手机板、FPC板、BGA、密脚IC、0201、01005元器件等

Main board, mobile phone board, FPC board, BGA, smart foot IC, 0201, 01005 components

技术参数 SPECIFICATION

项目 (Item)	YS-S7100	YS-S7100L
检测项目 Inspection Items		
检测内容 Inspection Items	锡膏印刷/红胶印刷: 体积、面积、高度、形状、偏移、桥连、溢胶 Solder printing/Red glue: Volume, Area, Height, Shape, Shift, Bridge, Overflow	
不良类型 NG Type	锡膏板: 漏印、多锡、少锡、连锡、偏位、形状不良、金手指 Solder paste: Missing, Excessive paste, Insufficient paste, Bridge, Paste deformity, Gold finger 红胶板: 溢胶、胶量不足 Red glue: Lack of glue, Glue overflow	
视觉光学系统 Visual Optical System		
相机 Camera	500万像素高速工业相机 5Mpixel high speed industrial camera	
光源 Light Source	R/G/B/W四色光源 RGBW light source	
光学解析度/FOV Optical Resolution/FOV	18um 36*36mm 15um 30*30mm	
投影头 Projection Head	摩尔光投影系统, 精准无阴影检测 Moire light projection system, accurate detection with no shadow	
速度与精度 Speed & Accuracy		
测试速度 Test Speed	0.35~0.42 sec/fov	
高度检测范围 Height Detection Range	1~1000um	
最大尺寸范围 Maximum Size Range	0.15x0.15mm~10x10mm	
高度检测分辨率 Height Detection Resolution	0.37 μm	
高度检测精度 Height Detection Accuracy	1um (基于校正块)	
重复性 Repeatability on a certificated Target	<1um@3sigma(高度 Height) <1%@3sigma(体积 Volume, 面积 area)	
重复性精度 Repeatability	<10%	
机台移动速度 Machine Moving Speed	700mm/s	
板弯补偿能力 Max PCB Warp	±5mm	
传送系统 Conveyor System		
驱动设备 Driver	交流伺服电机系统 AC Servo motor system	
PCB固定方式 PCB Fixed Mode	气压自动固定 Air pressure automatic fixed	
进出板模式 PCB Moving Mode	自动 Automatic	
宽度调整 Width Adjustment	自动 Automatic	
轨道高度 Conveyor Height	900 ± 20mm	
PCB尺寸 PCB Size	50x50mm~400x330mm	80x80mm~510x460mm
PCB厚度 PCB Thickness	0.5~5mm	
软件系统 Software System		
操作系统 Operation System	Microsoft Window 7x64	
编程方式 Programming	Gerber、CAD导入, 离线编程和手动编程 Gerber, CAD date, Offline programming and Manual programming	
统计过程控制 SPC	支持实时工程报表导出 Support real-time date report	格式: 图片、EXCEL Format: Pictures, EXCEL
通讯端口 Communication Port	SMEMA	
设备基本参数 Equipment Basic Parameters		
机械外形尺寸(W*L*H) Machine Dimension	950*960*1580mm 不含信号灯 Exclude Signal Light	1020*1090*1560mm 不含信号灯 Exclude Signal Light
重量 (kg) Weight	710KG	850KG
电源 Power	AC220V ± 10%、50Hz、1200W	
气源 Air Supply	4~6bar	

注: 规格如有变更, 恕不另行通知
Note: specifications are subject to change without notice



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